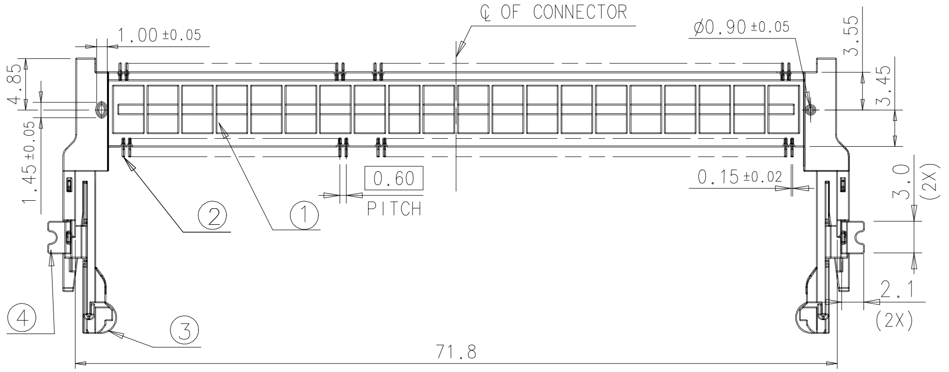
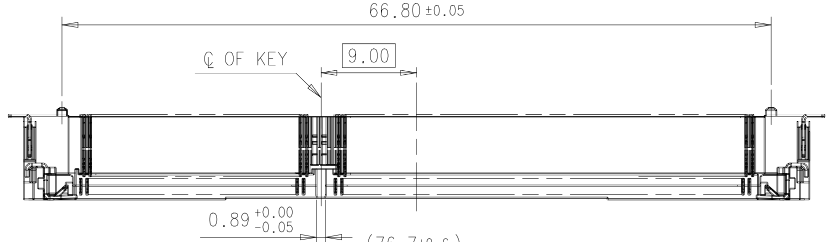
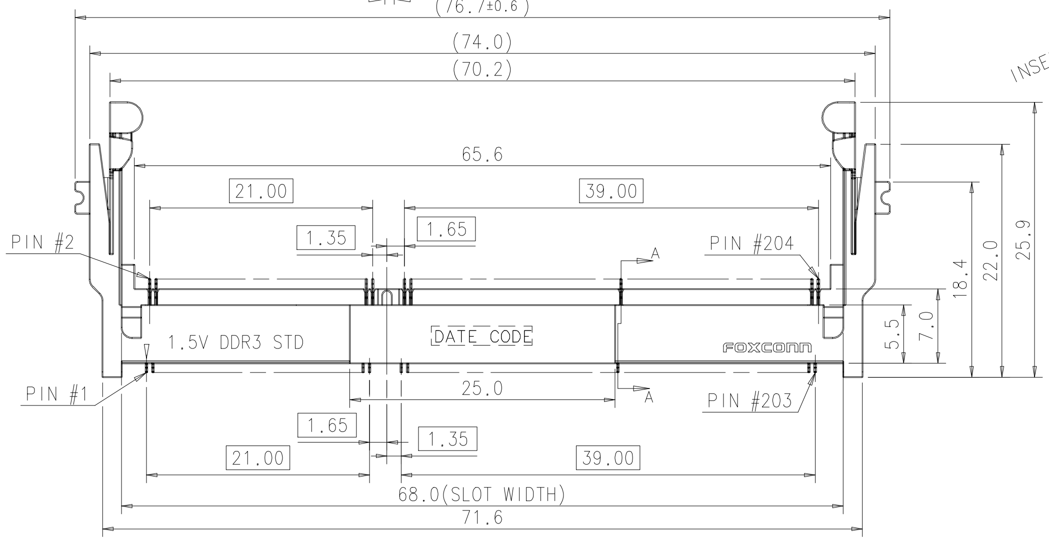
IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

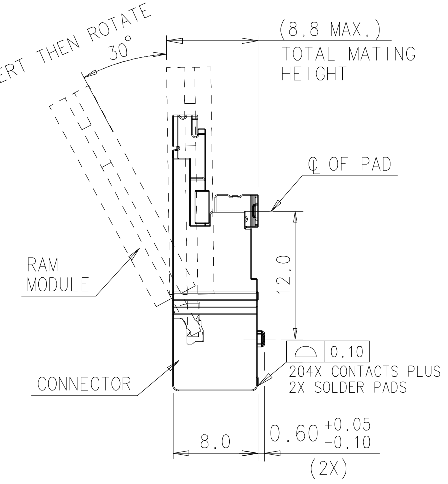
G	BC-14-0008184	C.S Li
H	BC-14-0010507	C.S Li

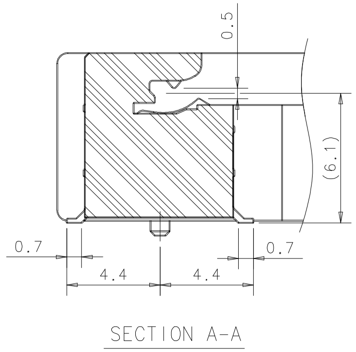
REV.	ECN. NO.	APPD.
A	BC-10-0100061	Herry Yang
B	BC-11-0038722	Herry Yang
C	BC-11-0049137	Herry Yang
D	BC-11-0119946	Herry Yang
E	BC-13-0004440	C.S Li
F	BC-13-0087027	C.S Li











NOTES:

1. ELECTRICAL CHARACTERISTICS:
   1.1. CONTACT CURRENT RATING: 0.5 AMPERE MAX. PER PIN.
   (PER PIN) DOESN'T EXCEED 30°C ABOVE AMBIENT AT 0.5 AMPERE MAX. PER PIN.
   1.2. VOLTAGE RATING: 25V AC.
   1.3. INSULATION RESISTANCE: 100 MEGAOHMS MIN. AT 500V DC.
   1.4. DIELECTRIC WITHSTANDING VOLTAGE: 250V AC RMS AT 60Hz,FOR 1 MINUTE.
   1.5. CONTACTRESISTANCE : 50 MILLIOHMS MAX. PER PIN INITIAL.
   60 MILLIOHMS MAX. PER PIN AFTER FULL ENVIRONMENTAL TESTING.
2. MECHANICAL CHARACTERISTICS: DURABILITY: 60 MATING CYCLES.
3. OPERATION TEMPERATURE: -55°C TO +85°C.
4. RECOMMENDED PROCESS CONDITION: SMT, PEAK TEMPERATURE:260°C, 10~20S.
5. PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAIL & AVAILABILITY.

PART NO. DESCRIPTION: A S 0 A6 2 * - H 8 S N-* H

MEMORY MODULE SOCKET
HORIZONTAL TYPE
SINGLE ROW
NO. OF POS.
A6 = 204 POS.
SMT
CONTACT AREA PLATING
1=GOLD FLASH
Y=5u" GOLD PLATING
6=10u" GOLD PLATING
7=15u" GOLD PLATING
3=30u" GOLD PLATING

H=HALOGEN FREE & LEAD FREE
4=SOFT TRAY
7=TAPE REEL
N=GENERAL TYPE
S=STANDARD
8=8.0mm HEIGHT
DDRIII SO DIMM

④	METAL PAD	2	COPPER ALLOY	50u" NICKEL UNDER PLATING OVER ALL 2u" Pd PLATING OVER SOLDER AREA
③	METAL SPRING	2	COPPER ALLOY	50u" NICKEL PLATING OVER ALL
②	CONTACT	204	COPPER ALLOY	50u" NICKEL UNDER PLATING GOLD FLASH AT TAIL GOLD FLASH OR 5u" OR 10u" OR 15u" OR 30u" GOLD PLATING AT CONTACT AREA
①	HOUSING	1	THERMOPLASTIC	UL94V-0, HALOGEN-FREE, IVORY COLOR
ITEM	DESCRIPTION	Q'TY	MATERIAL	TREATMENT

X. ± 0.30	X.° ±	UNITS mm	NAME(INTENDED USE) DDRIII SO DIMM CONNECTOR
.X ± 0.25	.X° ±	MAT'L	
.XX ± 0.15	.XX° ±		PART NO.(INTENDED USE) AS0A62*-H8SN-*H
.XXX ±	.XXX° ±	FINISH	APPD: C.S Li
		Q'TY	CHKD: ZH Wang
			DR: Wang Justin 3/5'14

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CLASS:
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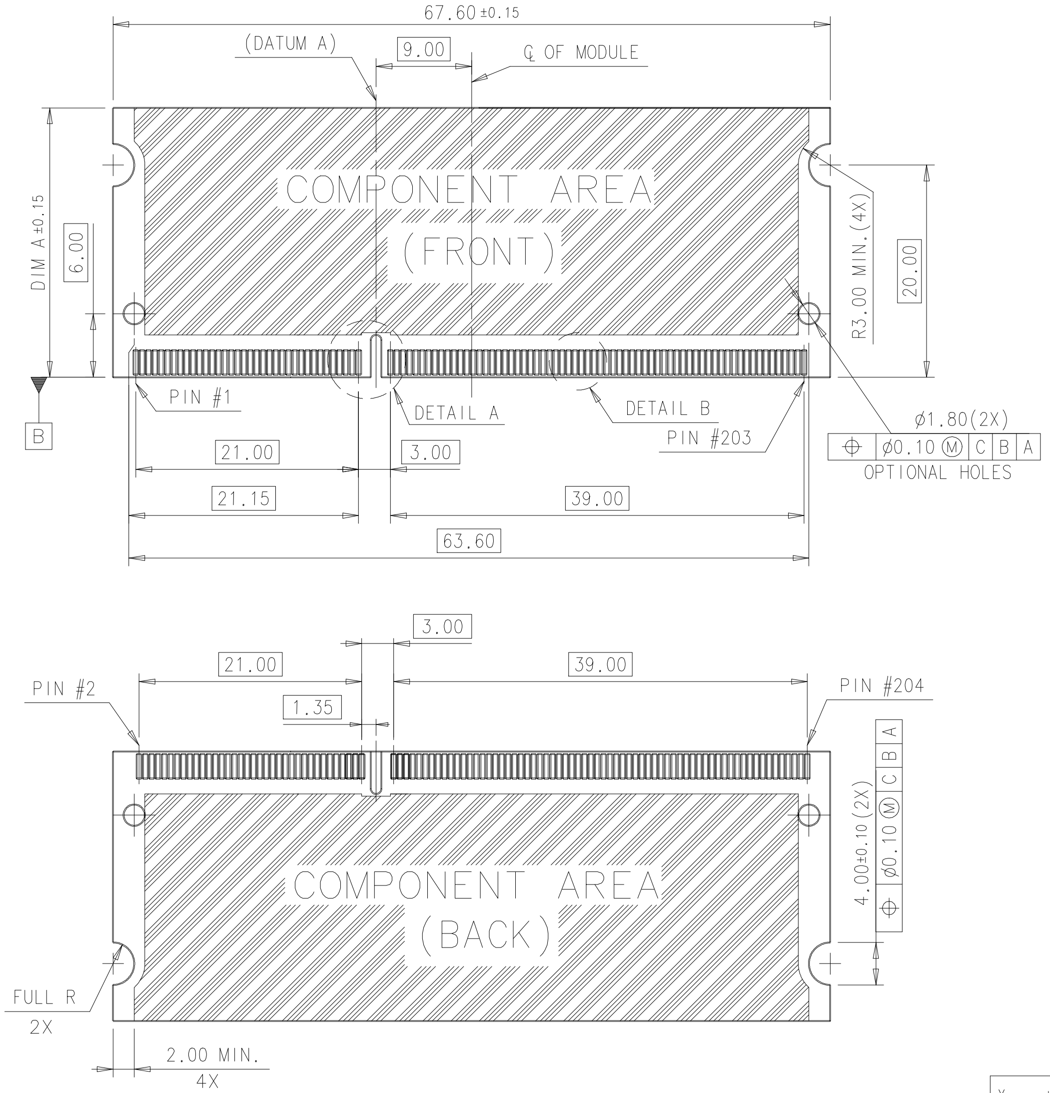
TITLE: CUSTOMER DRAWING
DWG NO.:
317-0000-1996

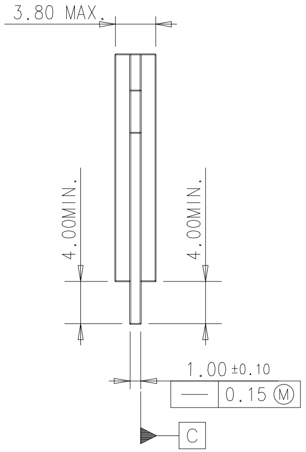
SCALE	SHEET	REV.
N/A	1/5	H

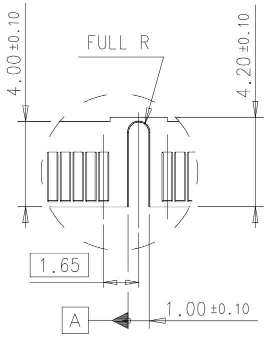
IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

REV.	ECN. NO.	APPD.

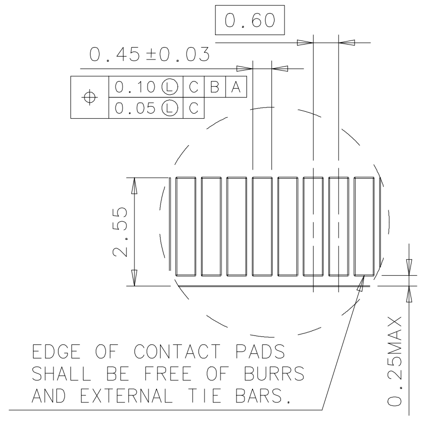


DDRIII SO-DIMM MODULE BOARD LAYOUT





DETAIL A



DETAIL B

SDRAM VARIATIONS	DIM A
TYPE 1	25.40
TYPE 2	31.75
TYPE 3	30.00

X. ± 0.25	X.° ±	UNITS mm
.X ± 0.10	.X° ±	MAT'L
.XX ± 0.05	.XX° ±	
.XXX ±	.XXX° ±	FINISH
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NAME(INTENDED USE)
DDRIII SO DIMM CONNECTOR
PART NO.(INTENDED USE)
AS0A62*-H8SN-*H
APPD: C.S Li
CHKD: ZH Wang
DR: Wang Jusrin 3/5'14

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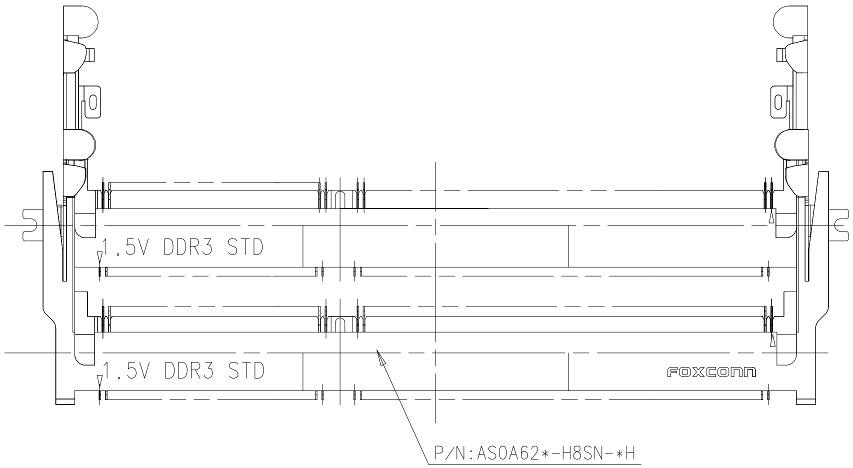
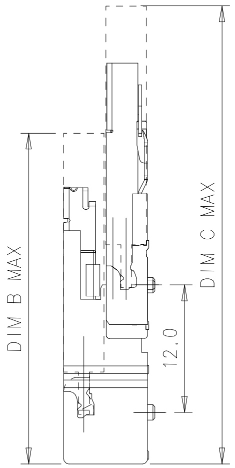
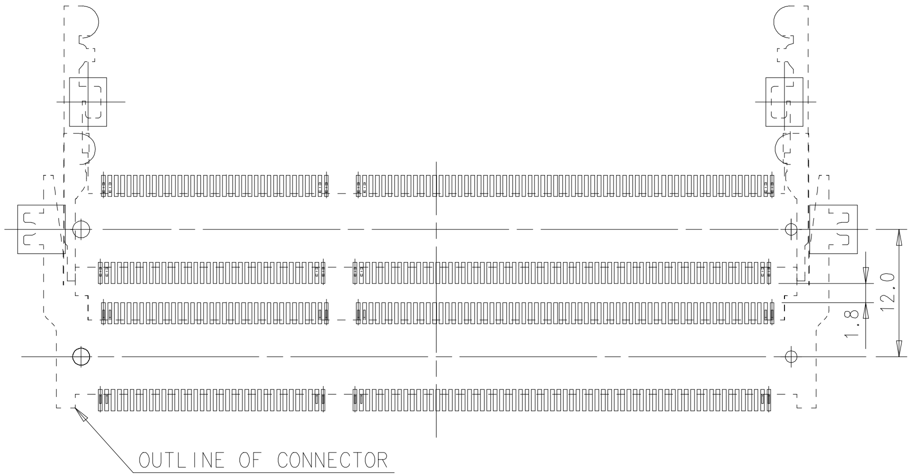
SCALE	SHEET	REV.
N/A	2/5	H

IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

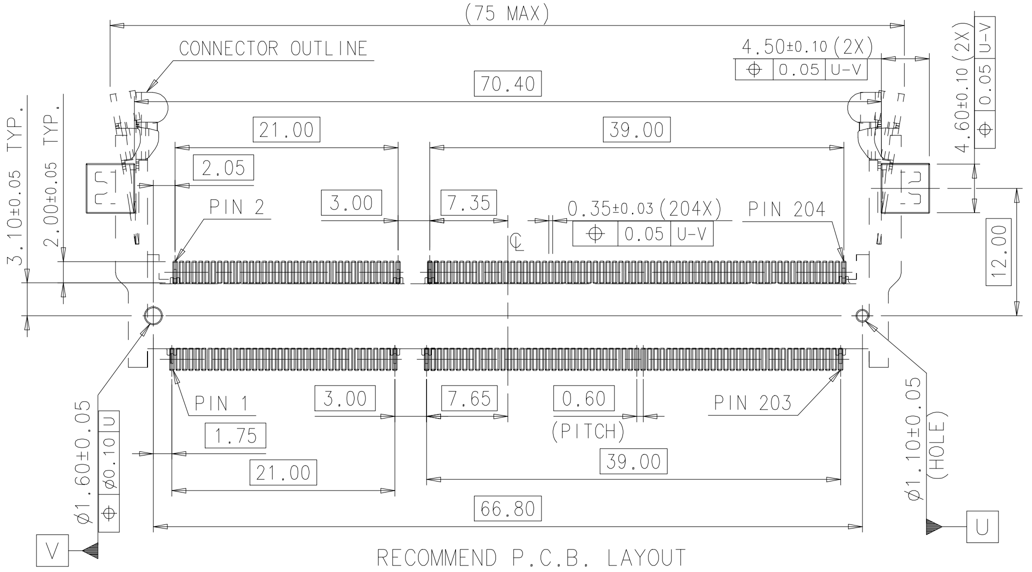
REV.	ECN. NO.	APPD.







P.C.B. LAYOUT(STACKED ORIENTATION)



RECOMMEND P.C.B. LAYOUT

SDRAM VARIATIONS	DIM B	DIM C
TYPE 1	30.4	42.4
TYPE 2	36.7	48.7
TYPE 3	35.0	47.0

X. ± 0.25	X.° ±	UNITS mm
.X ± 0.10	.X° ±	MAT'L
.XX ± 0.05	.XX° ±	
.XXX ±	.XXX° ±	FINISH

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Q'TY

NAME(INTENDED USE)
DDRIII SO DIMM CONNECTOR

PART NO.(INTENDED USE)
AS0A62*-H8SN-*H

APPD: C.S Li

CHKD: ZH Wang

DR: Wang Justin 3/5'14

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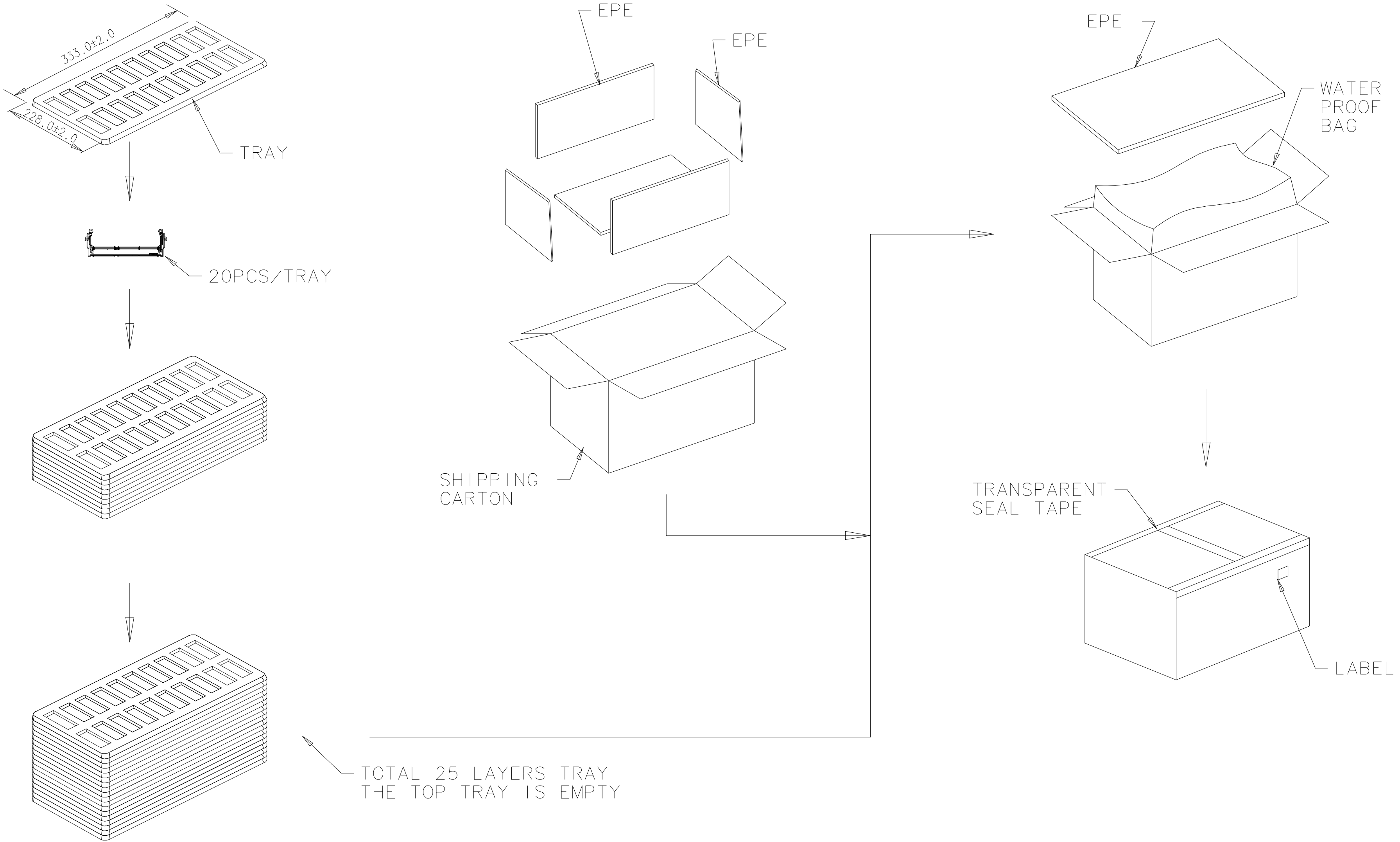
SCALE	SHEET	REV.
N/A	3/5	H

IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

REV.	ECN. NO.	APPD.



NOTES:

1. PACKING CAPACITY : 20 PCS/TRAY, 24 TRAYS/BOX,
   TOTAL 480 PCS/BOX.

CONNECTOR P/N	AS0A62*-H8SN-4H

X.	± 1.5	X.°	±
.X	± 1.0	.X°	±
.XX	± 0.5	.XX°	±
.XXX ±		.XXX° ±	

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UNITS mm

MAT'L

FINISH

Q'TY

NAME(INTENDED USE)
DDRIII SO DIMM CONNECTOR

PART NO.(INTENDED USE)
AS0A62*-H8SN-*H

APPD: C.S Li

CHKD: ZH Wang

DR: Wang Justin 3/5'14

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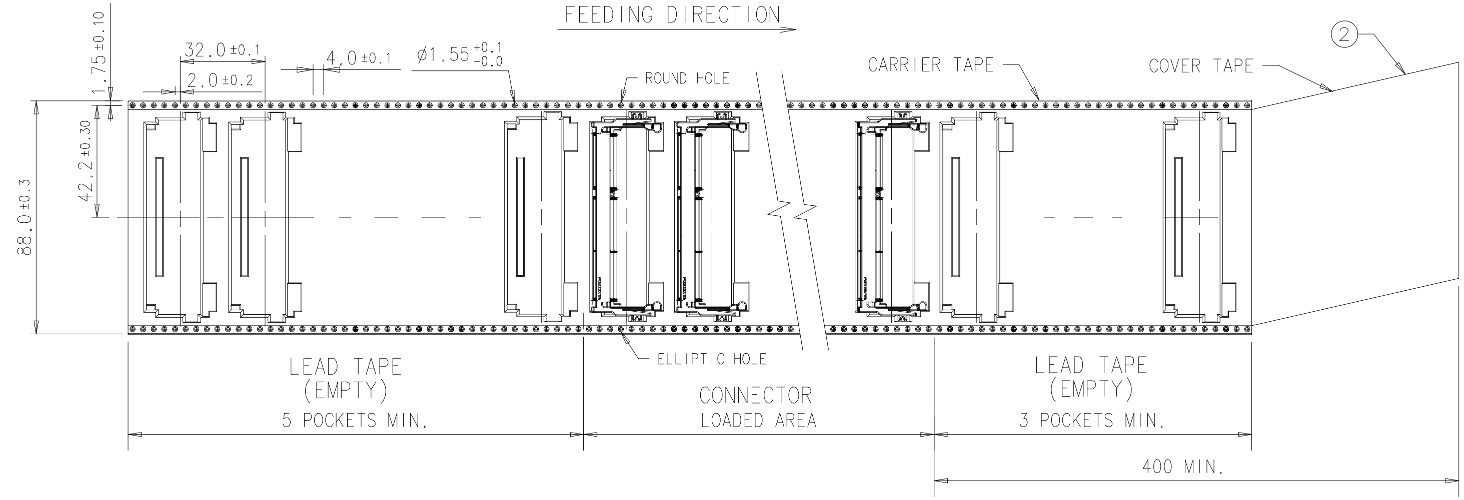
TITLE: CUSTOMER DRAWING

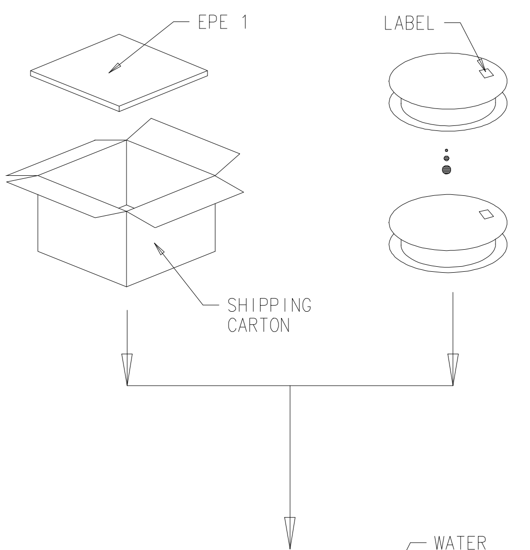
DWG NO.:
317-0000-1996

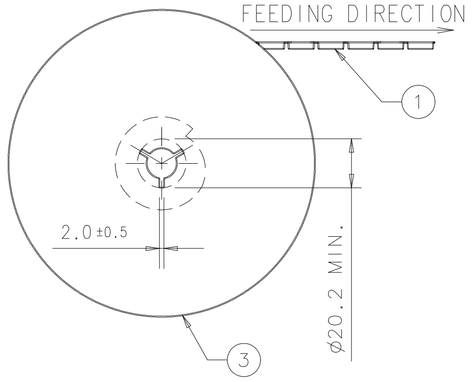
SCALE	SHEET	REV.
N/A	4/5	H

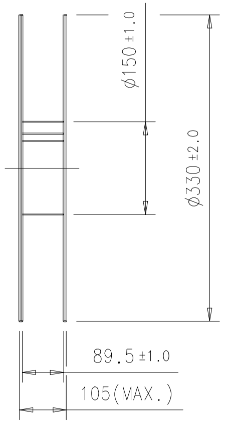
REV.	ECN. NO.	APPD.

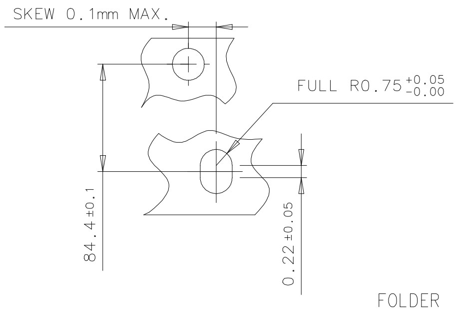
IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

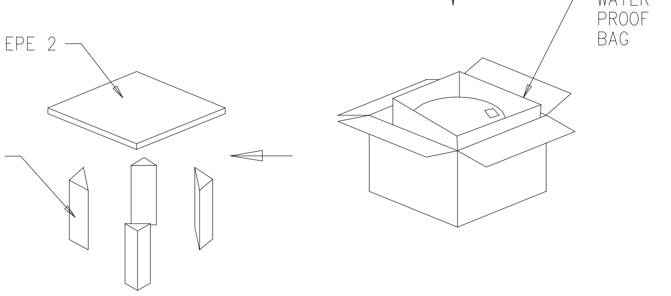


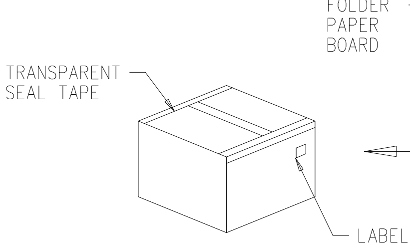




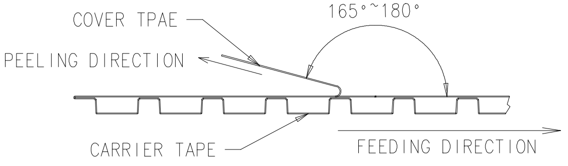








NOTES:
1. 10 POCKETS HOLE PITCH CUMULATIVE TOLERANCE ±0.20mm.
2. COVER TAPE PEELING STRENGTH : 0.01kgf MIN., 0.15 kgf MAX. AT 300mm/min.



3. PACKING CAPACITY : 140 PCS/REEL, 3 REELS/BOX,
TOTAL 420 PCS/BOX.

CONNECTOR P/N	AS0A62*-H8SN-7H

ITEM	DESCRIPTION	MATERIAL
③	REEL	POLYSTYRENE
②	COVER TAPE	POLYESTER
①	CARRIER TAPE	POLYSTYRENE

X. ± 1.5	X.° ±	UNITS mm	NAME(INTENDED USE) DDRIII SO DIMM CONNECTOR	**FOXCONN**® FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 1.0	.X° ±	MAT'L	PART NO.(INTENDED USE) AS0A62*-H8SN-*H	CLASS: ☐CONFIDENTIAL ☐SECRET ■GENERAL
.XX ± 0.5	.XX° ±	FINISH	APPD: C.S Li	TITLE: CUSTOMER DRAWING
.XXX ±	.XXX° ±	Q'TY	CHKD: ZH Wang	DWG NO.: 317-0000-1996
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